

Production Parameters:

Item	Production/Prototype
Layer Count	2-18L
Max Working Panel Size	24"x36"
Board thickness	0.008"-0.300"
Minimum finished board thickness	4L:0.016", 6L:0.024", 8L:0.032", 10L:0.048"
Minimum Hole Size	0.008" (Mechanical Drilling)
Minimum annular ring (Inner layer)	0.003"
Minimum annular ring (Outer layer)	0.003"
Min./Max. Core Thickness	0.004"-0.300"
Minimum thin core	0.004"
Inner Layer Min. Line/Space Width	0.003"/0.003"
Outer layer Min. Line/Space Width	0.003"/0.003"
Base copper thickness (Inner/Outer layer)	0.5-4.0oz
Min. Drill Size for PTH (Mechanical)	0.006"
Blind via (mechanical drilling) + buried via Mas. Aspect Ratio	11:1
Layer To Layer Registration	±0.002"
Routing Tolerance	±0.006"
Impedance Control Tolerance	28Ω ↑ ±10%



ROHS Directives



Good Price Offer



UL Registered Procedure



Reliable Quality Control



Surface Finishing:

Item	Production/Prototype
HASL with Lead Free	Yes
OSP	Yes
Immersion Gold	Yes
Immersion Silver	Yes
Immersion Tin	Yes
Gold Flash	Yes



ROHS Directives



Good Price Offer



UL Registered Procedure



Reliable Quality Control



Solder Mask

Item	Production/Prototype
Wet Film SM	Yes
Thermal Curing SM	Yes
UV Curing SM	Yes
Peelable SM	Yes
Blue	Yes
Green/Other Colour	Yes



ROHS Directives



Good Price Offer



UL Registered Procedure



Reliable Quality Control



Materials

Item	Production/Prototype
CEM-1	Yes
CEM-3	Yes
FR-1	Yes
FR-2	Yes
FR-4	Yes
FR-5	Yes
Teflon	Yes
Halogen Free	Yes
FR-4 High Tg	Yes
Rogers	Yes
Aluminum	Yes



ROHS Directives



Good Price Offer



UL Registered Procedure



Reliable Quality Control



Production Lead Time

Layers	Sample lead time	Mass Production Lead Time
2 Layers	5-7 days	12-14 days
4 Layers	7-10 days	14-16 days
6 Layers	10-13 days	18-21 days
8 Layers	14-16 days	21-24 days
10 Layers	18-21 days	24-26 days
12-18 Layers	21-24 days	26-30 days

